

STUDY OF THE MECHANICAL PROPERTIES OF a-SiC AND a-SiC_xN_y THIN FILMSM.A. Fraga^{1*}; M. Massi¹; I.O. Castro¹; N.C. Cruz²¹ ITA, Laboratório de Plasmas e Processos, 12.228-900, São José dos Campos, SP, Brazil² UNESP, Campus Experimental de Sorocaba, Laboratório de Plasmas Tecnológicos, 18.087-180, Sorocaba, SP, Brazil

Received: July 29, 2008; Revised: September 19, 2008

Keywords: amorphous films, magnetron sputtering, roughness, hardness, elastic modulus

ABSTRACT

This work describes the mechanical properties of a-SiC and a-SiC_xN_y thin films prepared by RF magnetron sputtering of a SiC target at different N₂/Ar gas flow ratios. Four different film compositions were studied. The elastic modulus and hardness of the films were determined by nanoindentation. Fourier transform infrared spectrometry (FTIR), Raman spectroscopy and atomic force microscopy (AFM) were used in order to investigate the influence of nitrogen content on the chemical bonds and morphology of the films.

1. INTRODUCTION

Silicon carbide (SiC) and silicon carbon nitride (SiCN) thin films have been recognized as a promising material for high-temperature micro-electro-mechanical (MEMS) systems due to its attractive properties such as high hardness, high chemical inertness and large band gap [1-2]. These properties are strongly dependent of Si, C and N contents in the films and can be altered by modifying the deposition conditions. Several techniques have been used to produce amorphous and crystalline forms of SiC and SiCN thin films, including plasma enhanced chemical vapor deposition (PECVD) [3], sputtering [4], atmospheric pressure chemical vapor deposition (APCVD) [5], and pulsed laser deposition (PLD) [6].

As shown in previous studies, the area of research in mechanical properties of SiCN ternary material and of the binary such as SiC, SiN, CN compounds is fairly open [7-8]. Mechanical properties of these thin films have been quite studied due to facilities provided by nanoindentation technique [9]. This technique offers capabilities to measure hardness and elastic modulus of films with few nanometers thickness. In addition, in this technique the influence of the substrate is eliminated since the maximum indentation depth remains lower than 10-15% of the film thickness [10].

Although some studies have been published on the mechanical properties of SiC_xN_y films, more investigations are needed to better understand the influence of nitrogen content on these properties. In this study, a-SiC and a-SiC_xN_y films have been deposited on p-type Si (100) substrates by

RF magnetron sputtering at different N₂/Ar flow ratios ($r=0, 0.1, 0.2, 0.3$).

Correlations between mechanical properties and the nitrogen content in the films have been evaluated by nanoindentation. We also studied the influence of nitrogen content on the morphological and structural properties of the films.

2. EXPERIMENTAL PROCEDURE

Amorphous SiC and SiC_xN_y films were deposited onto p-type (100) Si substrates by RF (13.56 MHz) magnetron sputtering of a SiC target (99.5% purity) in an argon-nitrogen plasma. The target-substrate distance was fixed at 75 mm. Different film compositions were obtained by varying the nitrogen flow rate while the other parameters were kept constant. Table 1 summarizes the deposition conditions.

Table 1 – Deposition conditions of the films

Parameter	Value
N ₂ flow (sccm)	0 to 2,1
Ar flow (sccm)	7,0
RF power (W)	200
Working pressure (Torr)	2 x 10 ⁻⁶
Time (min)	120

The chemical bonding of the films have been investigated by Fourier transform infrared spectrometry (FTIR) and Raman spectroscopy. Infrared spectroscopy was performed by a Perkin Elmer spectrum 2000 Fourier transform infrared spectrometer in the range 400–4000 cm⁻¹. A (100) silicon wafer was used as reference. Raman spectroscopy was performed with a Renishaw 2000 system using an Ar⁺-ion laser ($\lambda = 514$ nm) with power 0.6 mW. Raman spectra were obtained at room temperature in the range of 400 to 2000 cm⁻¹. AFM images were obtained by a SPM-9500J3 system in dynamic mode. The thickness of each sample was obtained by measuring step heights using profilometry (TENCOR Alpha-Step 500 profilometer).

Elastic modulus and hardness of the films were determined by nanoindentation technique using a Hysitron triboindenter. In this technique, a controlled load is applied to a diamond tip in contact with the surface. The continuous mea-

* mafraga@ita.br

surement of the tip displacement as the applied allowed the construction of load-unload curves.

3. RESULTS AND DISCUSSION

3.1 CHEMICAL BONDING

Figure 1 shows transmission FTIR spectra of a-SiC and a-SiC_xN_y thin films in the range of 400 – 4000 cm⁻¹. As can be observed, the a-SiC film (sample B0) presents bands at around 841 cm⁻¹ and 1108 cm⁻¹ that associated to Si-C and Si-O stretching vibration modes respectively.

These vibrational modes also appear in the spectra of all samples of a-SiC_xN_y films. In addition, the sample B3 deposited under higher nitrogen flow also present bands at around 1200 cm⁻¹ and 1540 cm⁻¹ corresponding to Si-N and C-N bonds respectively.

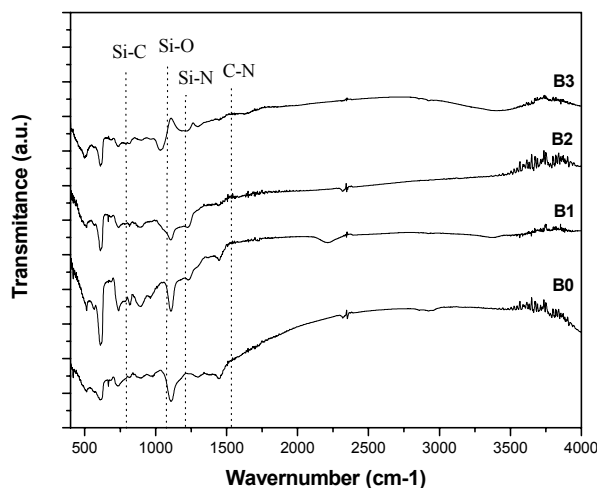


Figure 1 - FTIR spectra of the SiC film (sample B0) and a-SiC_xN_y films deposited at different N₂/Ar flow ratios.

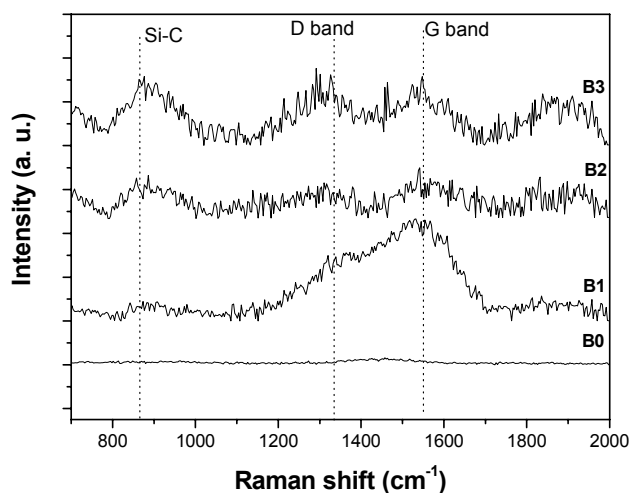


Figure 2 - Raman spectra of the SiC film (sample B0) and a-SiC_xN_y films deposited at different N₂/Ar flow ratios.

Additional information about chemical bonds can be obtained from Raman spectra of the films shown in Figure 2. Raman spectrum of the SiC film (sample B0) does not present evidences of any peak corresponding to Si-C or C-C bonds. On the other hand, the SiC_xN_y films present a relatively weaker band around 830 cm⁻¹ which is typical of amorphous SiC structure and show intense and broader bands, centered around 1350 cm⁻¹ and 1580 cm⁻¹, that are characteristics of C-C bonds recognized as D and G band, respectively.

Some studies [8,11] show that the existence of G band in SiC_xN_y films indicate the formation of CN_x phases.

3.2 THICKNESS, ROUGHNESS AND SURFACE MORPHOLOGY

The thickness and roughness of the a-SiC and SiC_xN_y films were determined by profilometry and atomic force microscopy (AFM) respectively. Figure 3 shows the results obtained as a function of nitrogen flow rate.

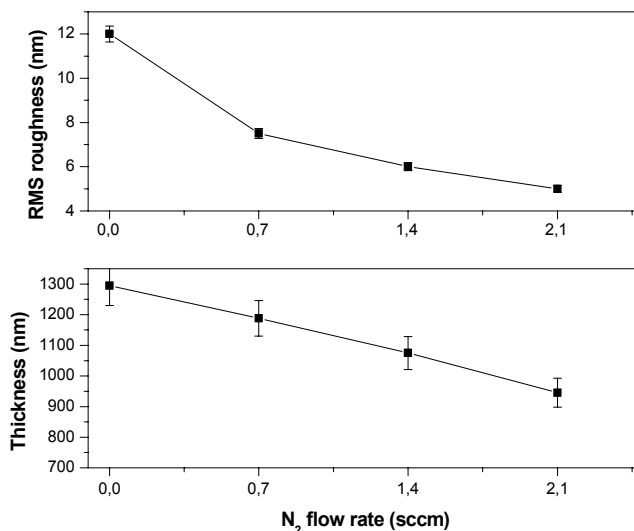


Figure 3 - RMS roughness and thickness of the a-SiC and a-SiC_xN_y films as a function of N₂ flow rate

It was observed that the addition of nitrogen in the sputtering process promotes a reduction in the RMS roughness and an increase in the thickness of the films.

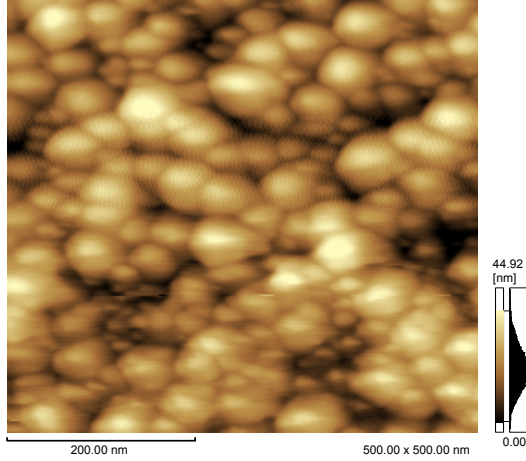
AFM images of the films (see Figure 4) indicate that the SiC_xN_y films are much smoother than SiC film. This can be understood by the fact that the films are formed by a reactive process. Therefore, higher nitrogen flow rate increases the reactive process allowing the formation of denser films with fewer voids.

3.3 MECHANICAL PROPERTIES

The nanoindentation technique is widely used approach for the determination of hardness and elastic modulus of thin films, which can be obtained through an interpretation of

experimentally obtained load–displacement curves during the indentation load /unload cycle [12–13].

(a)



(b)

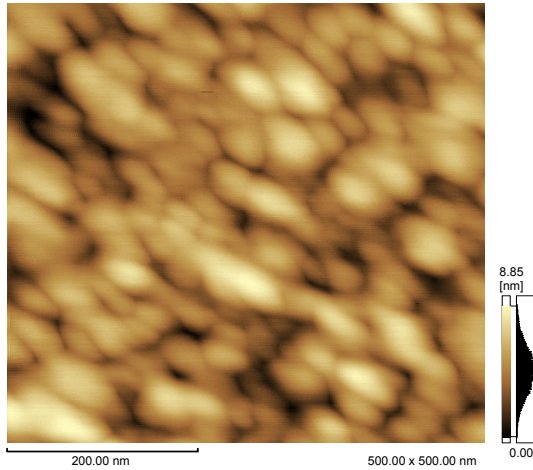


Figure 4 - AFM images of the surface of: (a) a-SiC film (sample B0) and (b) a-SiC_xN_y films (sample B2).

In this work, nanoindentation testing with a Berkovich diamond indenter (a three-sided pyramid) was used to measure the reduced elastic modulus (E) and hardness (H) of the a-SiC and a-SiC_xN_y films. The physical principles to determine E and H are based on the Oliver-Pharr theory [14]. The fundamental relations to calculate hardness and reduced elastic modulus are:

$$H = \frac{P_{\max}}{A} \quad (1)$$

$$E_r = \frac{\sqrt{\pi}}{2} \frac{S}{\sqrt{A}} \quad (2)$$

where $P_{\max}$ is the peak load, S is the parameter known as the elastic contact stiffness and A is the projected contact area at that load that for a Berkovich tip is defined by:

$$A = 24.5h_c^2 \quad (3)$$

where h_c is the final plastic contact depth.

The elastic modulus of the material, E , is then calculated from E_r by the expression:

$$\frac{1}{E_r} = \frac{1-\nu^2}{E} + \frac{1-\nu_i^2}{E_i} \quad (4)$$

where ν_i , ν , E_i and E are the Poisson's ratio and Elastic modulus of the indenter and sample, respectively. In this study, we used a diamond indenter with $E_i = 1141$ GPa and $\nu_i = 0,07$.

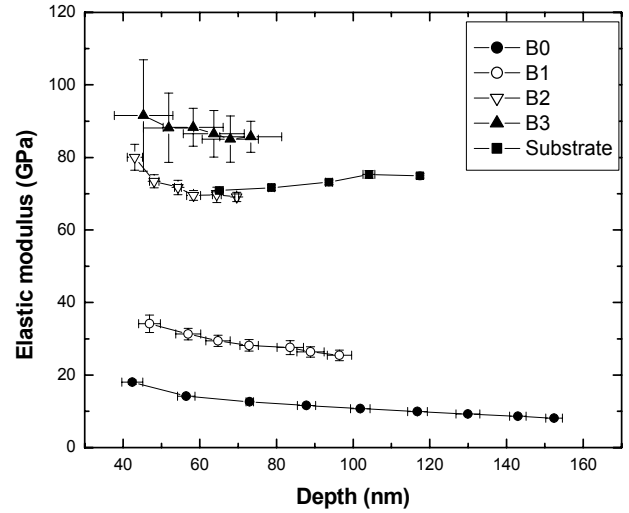


Figure 5 - Elastic modulus of of SiC film (sample B0) and a-SiC_xN_y films as a function of indentation depth.

Figures 5 and 6 show the elastic modulus and hardness values of the a-SiC and a-SiC_xN_y films as a function of indentation depth. The values obtained indicate that the hardness and elastic modulus of the films increase with nitrogen flow rate increases. This increase is due to formation of C-N and Si-N bonds in the films.

4. CONCLUSION

The mechanical properties of a-SiC and a-SiC_xN_y thin films deposited by RF magnetron sputtering have been investigated. Hardness and elastic modulus were determined by nanoindentation, an increase in their values was observed as a function of nitrogen flow rate increases. The results indicate that the films had a range from 3.8 to 9.2 GPa for the hardness and 17 to 92 GPa for the elastic modulus when the N₂

flow rate is varied from 0 to 2.1 sccm. FTIR and Raman spectra indicated the existence Si-C, Si-N and C-N phases in the films. AFM analysis showed that the films become smoother as the nitrogen flow rate ratio increases.

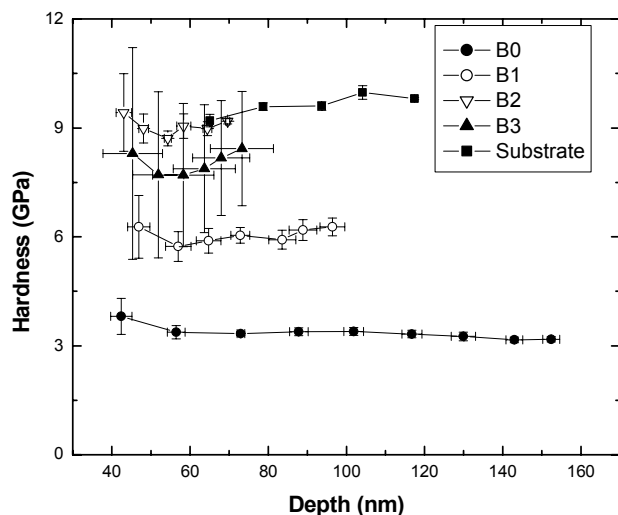


Figure 6 - Hardness of SiC film (sample B0) and a-SiC_xN_y films as a function of depth.

ACKNOWLEDGEMENTS

The financial support of CNPq is strongly acknowledged. The authors also thank Dr. Rita C. L. Dutra e Dr. Marta F. K. Takahashi (from IAE-AQI) for FTIR analyses, Dr. Lúcia Vieira dos Santos and Dr. Luis Francisco Bonetti for providing the facilities for the use Raman system and profilometer at INPE.

REFERENCES

- HE, Z.; CARTER, G.; COLLIGON, J.S., *Thin Solid Films* 283 (1996) 90.
- JEDRZEJOWSKI, P.; CIZEK, J.; AMASSIAN, A.; KLEMBERG-SAPIEHA, J.E.; VLCEK, J.; MARTINU, L., *Thin Solid Films* 447-448 (2004) 201.
- SACHDEV, H.; SCHEID, P., *Diamond and Related Materials* 10 (2001) 1160.
- HOCHE, H.; ALLEBRANDT, D.; BRUNS, M.; RIEDEL, R.; FASEL, C., *Surface and Coatings Technology* 202 (2008) 5567.
- LIEW, L.; LIU, Y.; LUO, R.; CROSS, T.; AN, L.; BRIGHT, V.M.; DUNN, M.L.; DAILY, J.W.; RAJ, R., *Sensors and Actuators A: Physical* 95 (2002) 120.
- SOTO, G.; SAMANO, E.C.; MACHORRO, R.; COTA, L., *Journal of Vacuum Science and Technology A* 16 (1998), 1311.
- CHEN, L.C.; CHEN, K.H.; WEI, S.L.; KICHAMBARE, P.D.; WU, J.J.; LU, T.R.; KUO, C.T., *Thin Solid Films* 355-356 (1999) 112.
- SUNDARAM, K.B.; ALIZADEH, Z.; TODI, R.M.; DESAI, V.H., *Materials Science and Engineering A* 368 (2004) 103.
- OLIVER, W.C.; PHARR, G.M., *Journal of Materials Research* 19 (2004) 3.
- FERNANDES, J.V.; TRINDADE, A.C.; MENEZES, L.F.; CAVALEIRO, A., *Journal of Materials Research* 15 (2000) 1766.
- CHENG, Y.; TAY, B.K.; LAU, S.P.; SHI, X.; QIAO, X.L.; CHEN, J.G.; WU, Y.P.; XIE, C.S., *Applied Physics A* 73 (2001) 341.
- HAY, L.; PHARR, G.M., *Instrumented Indentation Testing ASM Handbook - Volume 08: Mechanical Testing and Evaluation 06772G*, ASM, Ohio, 2000.
- LI, X.; BHUSHAN, B., *Materials Characterization* 48 (2002) 11.
- OLIVER, W.C.; PHARR, G.M., *Journal of Materials Research* 7 (1992) 1564.